

GigaDevice	USON6	1.2mmx1.2mm
USON8	3mmx2mm	
FO-USON8	3mmx2mm	
FO-USON8	3mmx3mm	
USON8	4mmx4mm	
WSON8	6mmx5mm	

SPI NOR Flash系列 超小封装

兆易创新SPI NOR Flash系列拥有多种小封装选择，包括USON6（1.2mmx1.2mm），WLCSP，FO-USON8（3mmx3mmx0.4mm）和FO-USON8（3mmx2mmx0.4mm），为物联网（IoT）设备、可穿戴设备、智能手机以及各种紧凑型电池供电应用提供了极大的设计灵活性。

USON6 1.2mmx1.2mm封装产品

Voltage	Density	Part No.	Frequency	Key Feature	Temperature
1.65V~2.0V	2Mb	GD25LD20EK6xx	50MHz (x1) 40MHz (x2)	STR Dual Output, Zero Standby	-40°C~+85°C -40°C~+105°C -40°C~+125°C
	4Mb	GD25LD40EK6xx	50MHz (x1) 40MHz (x2)	STR Dual Output, Zero Standby	
1.65V~3.6V	1Mb	GD25WD10EK6xx	104MHz (x1) 80MHz (x2)	STR Dual Output, Zero Standby	
	2Mb	GD25WD20EK6xx	104MHz (x1) 80MHz (x2)	STR Dual Output, Zero Standby	
	4Mb	GD25WD40EK6xx	104MHz (x1) 80MHz (x2)	STR Dual Output, Zero Standby	

WLCSP封装技术

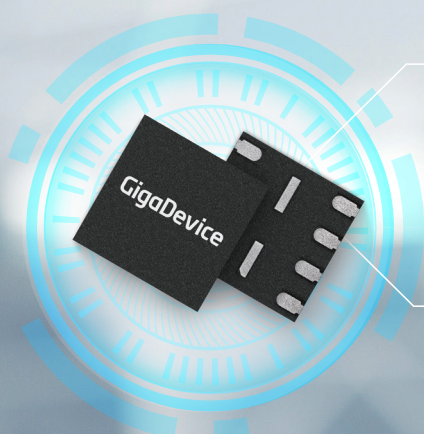
小尺寸、低功耗 让有限空间释放无限创意

兆易创新WLCSP封装体积紧凑，能够使设计人员最大化利用PCB空间。WLCSP封装是最小尺寸的封装方式，与芯片尺寸相同。该封装产品提供1.2V和1.8V低电压供电，可满足包括手机在内的低功耗紧凑型移动设备的设计需求。

WLCSP封装产品

Voltage	Density	Part No.	Frequency	Key Feature	Package
1.14V~1.26V	64Mb	GD25UF64ELIGR	120MHz (x1, x2, x4) 80MHz (DTR)	STR, DTR Quad I/O, Default x4 I/O	WLCSP (4-4 ball array)
1.65V~2.0V	8Mb	GD25LE80ELIGR	133MHz (x1, x2, x4)	STR Quad I/O, Low Power	WLCSP (4-4 ball array)
	16Mb	GD25LE16E3IGR	133MHz (x1, x2, x4)	STR Quad I/O, Low Power	WLCSP (3-2-3 ball array)
	32Mb	GD25LE32E3IGR	133MHz (x1, x2, x4)	STR Quad I/O, Low Power	WLCSP (3-2-3 ball array)
	64Mb	GD25LE64ELIGR	133MHz (x1, x2, x4)	STR Quad I/O, Low Power	WLCSP (4-4 ball array)
	128Mb	GD25LE128ELIGR	133MHz (x1, x2, x4)	STR Quad I/O, Low Power	WLCSP (4-4 ball array)
	256Mb	GD25LE255ELIGR	133MHz (x1, x2, x4)	STR Quad I/O, Low Power	WLCSP (4-4 ball array)
	256Mb	GD25LX256E4IRR	200MHz (x1, x8) 200MHz (DTR)	STR, DTR Octal I/O, ECC	WLCSP (4x6 ball array)
	512Mb	GD25LB512ME3IRR	166MHz (x1, x4) 90MHz (DTR)	STR, DTR Quad I/O, Default x4 I/O	WLCSP (3-2-3 ball array)

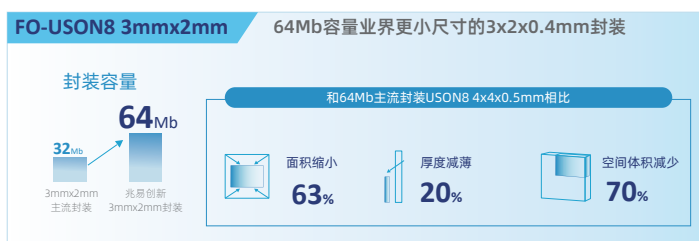
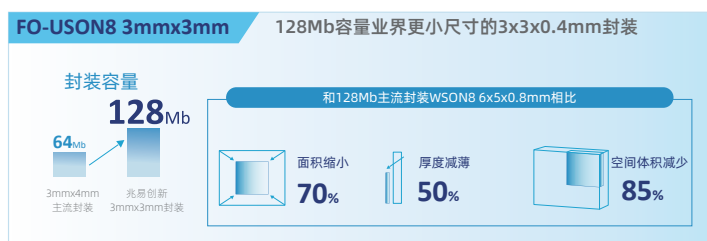




FO-USON8 (3x3x0.4mm/3x2x0.4mm)

兆易创新 3x3x0.4mm/3x2x0.4mm FO-USON8 封装以其0.4mm的超薄厚度（最大值），为设计人员在紧凑型应用中提供了极大的灵活性。该封装成为物联网、可穿戴设备、医疗保健和网络等领域高性能、低功耗产品的理想选择。

扩大同封装容量



FO-USON8 3mmx3mm 封装产品

Voltage	Density	Part No.	Frequency	Key Feature	Temperature
1.65V~2.0V	128Mb	GD25LE128EXHxx	133MHz (x1, x2, x4)	STR Quad I/O, Low Power	-40°C~+85°C -40°C~+105°C -40°C~+125°C
		GD25LF128EXHxx	166MHz (x1, x2, x4) 104MHz (DTR)	STR, DTR Quad I/O, Default x4 I/O	
		GD25LQ128EXHxx	133MHz (x1, x2, x4)	STR Quad I/O	

FO-USON8 3mmx2mm 封装产品

Voltage	Density	Part No.	Frequency	Key Feature	Temperature
1.65V~2.0V	64Mb	GD25LE64EXExx	133MHz (x1, x2, x4)	STR Quad I/O, Low Power	-40°C~+85°C -40°C~+105°C -40°C~+125°C
		GD25LF64EXExx	166MHz (x1, x2, x4) 104MHz (DTR)	STR, DTR Quad I/O, Default x4 I/O	
		GD25LQ64EXExx	133MHz (x1, x2, x4)	STR Quad I/O	
2.7V~3.6V		GD25Q64HXExx	133MHz (x1, x2, x4) 80MHz (DTR)	STR, DTR Quad I/O	
1.65V~3.6V		GD25WQ64HXExx	104MHz (x1, x2, x4)	STR Quad I/O	

